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Business Segment: ELECTRONICS

MACDERMID ALPHA ANNOUNCES THE RELEASE OF M-CONTACT IN-2000: REEL TO REEL INDIUM PLATING FOR PRESS-FIT CONNECTOR FINISHING

(Waterbury, CT USA) – April 4, 2019 – MacDermid Alpha Electronics Solutions announced the release of M-Contact IN-2000 for sales worldwide. The M-Contact IN-2000 is an acid indium electroplating process for press-fit connector plating that is fully analyzable and easy to control. The indium deposit produced by the IN-2000 bath is naturally resistant to whiskering. With a wide current density range, greater than 90% plating efficiency over the life of the bath, and resistance to many different metallic bath contaminants, the IN-2000 is an excellent coating for any metal sub-layer.

Rich Bellemare, Director for Electrolytic Metallization, Circuitry Solutions noted, “Fabricators that manufacture connectors, especially those for automotive applications, have been searching for ways to reduce reliance on tin finishes for many years. With the M-Contact IN-2000, we finally can offer an alternative to tin that provides a complete solution ready for specification. “

The M-Contact IN-2000 process is the latest expansion to the MacDermid Enthone brand family of connector plating chemistries that allows for highly customized stack combinations including copper, nickel, nickel alloys, palladium, tin, silver, gold and other precious metals.

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